

**Supplemental Preliminary Amendment**

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Title: ELECTRONIC COMPONENT AND A PANEL (As Amended)

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**IN THE ABSTRACT**

Please replace the Abstract beginning on page 13, line 5, of the Substitute Specification with the following rewritten Abstract.

**ELECTRONIC COMPONENT AND A PANEL ~~FOR ITS PRODUCTION~~**

**ABSTRACT**

One embodiment of ~~the~~ invention relates to an electronic component ~~(1)~~ having stacked semiconductor chips ~~(3, 4)~~, and to a panel ~~(23)~~ for production of the component ~~(1)~~. ~~On~~ In one case, ~~For this purpose,~~ the stack ~~(2)~~ has a flat conductor structure ~~(8)~~ with a chip island ~~(9)~~ on which a stacked semiconductor chip ~~(4)~~ is arranged, while a first semiconductor chip ~~(3)~~ is located underneath it. The chip island ~~(9)~~ is surrounded by flat conductors ~~(10)~~ which have contact pillars ~~(11)~~. These contact pillars ~~(11)~~ have pillar contact pads ~~(13)~~ which, together with the active upper face ~~(5)~~ of the first semiconductor chip ~~(3)~~ and the upper face areas ~~(14)~~ of a plastic encapsulation compound ~~(15)~~ form a coplanar overall upper face ~~(16)~~.